

# Hermetic Packaging - Global Market Outlook (2018-2027)

<https://marketpublishers.com/r/HFB775161A5AEN.html>

Date: September 2019

Pages: 176

Price: US\$ 4,150.00 (Single User License)

ID: HFB775161A5AEN

## Abstracts

According to Statistics MRC, the Global Hermetic Packaging market accounted for \$3.27 billion in 2018 and is expected to reach \$6.98 billion by 2027 growing at a CAGR of 8.8% during the forecast period. Rising demand for energy, Growing adoption for protecting highly sensitive electronic components and increase in global aerospace and defense expenditure are the key factors driving the market growth. However, stringent standards may hinder the market growth.

Hermetic packaging is defined as propelled level bundling system which has its essential applications in electronic gadgets and it also has a usage in the semiconductor and electronics industry. This sort of packaging prevents liquids and gases from entering the package cavity. Additionally, owing to the hermetic package materials, these can withstand and work in higher temperatures. Moreover, this bundling keeps the semiconductor part from any kind of corrosion more productively than any other identical plastic packaging.

By Type, the Ceramic–Metal (CERTM) Sealing segment is constantly enhancing during forecast period due to the growing warm stun safe and low-porosity sort of hermetic packaging material. The CERTM sealed sensors are discovering potential applications in the automobile as they assure the safety of the passengers while offering failure-free operation. Based on geography, Asia Pacific is likely to have a huge demand attributed to the increasing energy needs in developing countries, such as China and India. Also, many countries in this region are now stepping up in space research activities, such as satellite launches and space exploration missions, which is expected to add to the high growth of the hermetic packaging market in APAC during the forecast period.

Some of the key players profiled in the Hermetic Packaging market include Texas

Instruments, Schott, Micros Components, SGA Technologies, Complete Hermetics, Teledyne Microelectronics, Legacy Technologies, SHP, Egide, Willow Technologies, Materion, Ametek, Kyocera, Amkor, and Intersil.

Types Covered:

Transponder Glass

Ceramic–Metal (CERTM) Sealing

Glass–Metal Sealing (GTMS)

Passivation Glass

Reed Glass

Material Types Covered:

Isotropic

Anisotropic

Configurations Covered:

Metal Can Packages

Multilayer Ceramic Packages

Pressed Ceramic Packages

Closing Techniques Covered:

Soldering

Crimp Connection

Welding

Applications Covered:

Industrial Equipments

Microelectromechanical systems (MEMS) Switches

Oscillating Crystals

Transistors

Airbag Ignitors

Photodiodes

Sensors

Lasers

Other Applications

End Users Covered:

Telecommunications

Military & Defense

Automotive

Consumer Electronics

Medical

Aeronautics and Space

Energy and Nuclear Safety

Other End Users

Regions Covered:

North America

US

Canada

Mexico

Europe

Germany

UK

Italy

France

Spain

Rest of Europe

Asia Pacific

Japan

China

India

Australia

New Zealand

South Korea

Rest of Asia Pacific

South America

Argentina

Brazil

Chile

Rest of South America

Middle East & Africa

Saudi Arabia

UAE

Qatar

South Africa

Rest of Middle East & Africa

What our report offers:

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Strategic recommendations for the new entrants

Market forecasts for a minimum of 9 years of all the mentioned segments, sub segments and the regional markets

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Strategic recommendations in key business segments based on the market estimations

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Market estimations, Forecasts and CAGR of any prominent country as per the clients interest (Note: Depends of feasibility check)

##### Competitive Benchmarking

Benchmarking of key players based on product portfolio, geographical presence, and strategic alliances

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